Micron Technology Samples New Single-Sided DDR3 Dram Module and TE Connectivity Releases Compatible, Single-Sided DDR3 Module Connectors

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BOISE, Idaho and SHANGHAI, Feb. 7, 2013 (GLOBE NEWSWIRE) -- Micron Technology, Inc. (Nasdaq:MU), one of the world's leading providers of advanced semiconductor solutions, and TE Connectivity (TE) (NYSE:TEL), a world leader in connectivity, announced today the availability of a Single-Sided SODIMM and a low-profile single-sided, double data rate 3 (DDR3) SODIMM connector solution to take advantage of the burgeoning market for Ultrabook™ devices, convertibles, tablets and other thin and light devices. Aimed at providing a reduced-height memory solution for the ultrathin computing market, the new Single-Sided SODIMM, developed by Micron, has components on either the front or back side of the module, but not both. When paired with the single-sided DDR3 SODIMM connector from TE, the total z-height of the overall solution from the motherboard is just 3mm, a 35 percent savings compared to 4.6mm for a standard SODIMM solution.

Micron's Single-Sided SODIMM is available in a 4GB, single-rank, x8 configuration. In addition to a reduced height, this new module is built using 30nm DDR3L-RS components that consume less power in standby compared to standard DDR3. Additionally, Single-Sided SODIMMs are pin-to-pin compatible with current DDR3 modules, making them backward compatible with existing DDR3 SODIMM connectors.

"Given the depth and breadth of ultrathin devices currently on the market, coupled with consumer demands for sleek, lightweight designs, Micron's objective is to offer solutions that meet the specialized power, portability and battery life needs," said Kris Kido, Micron's Director of Business Development, Computing Devices. "Micron's unique Single-Sided SODIMM form factor meets those requirements and leads the way for future developments in this growing segment."

TE engineers designed the new single-sided DDR3 SODIMM connector to deliver peak performance with high-speed data applications. The connector features a 35 percent reduction in height, compared with similar low-profile connectors, which in turn, reduces the height of the end-product by 5 to 10 percent. It also reduces motherboard shadow area by nearly 156 mm^2, or 312 mm^2 for common dual-socket implementation. The DDR3 SODIMM connector accepts modules that meet JEDEC MO268 industry standards and is offered in both standard and reverse types.

"It's clear that we're seeing devices, ranging from Ultrabook™ devices to tablets, become increasingly thinner and sleeker," said Hook Chang, product manager, TE Consumer Devices. "In the past, the miniaturization of circuitry-powering device memory often compromised reliability. Our DDR3 SODIMM connector solves that problem, ensuring durable connectivity to optimize device functionality, speed and usability. Micron Technology shares our commitment to provide consumers with high-quality, reliable cost-effective solutions to maximize product performance."

Availability

Single-Sided SODIMM samples are available from Micron now, with mass production scheduled for Spring, 2013.

Single-Sided SODIMM connector samples are available from TE Connectivity now, with mass production scheduled for June, 2013.

Micron Ultrathin Memory: Embracing the Future

With a global view of the mobile computing market, Micron is well positioned to support the growth of ultrathin applications. Our broad portfolio of industry-leading DRAM, SSD and NOR flash make high-performance, ultrathin computing come to life in the time it takes to snap your finger. Powerful, highly-responsive computing, instant-on/instant-off, rapid application load times, super slim and light designs, longer battery life and better power savings are all possible with Micron's memory and storage solutions.

About Micron

Micron Technology, Inc., is one of the world's leading providers of advanced semiconductor solutions. Through its worldwide operations, Micron manufactures and markets a full range of DRAM, NAND and NOR flash memory, as well as other innovative memory technologies, packaging solutions and semiconductor systems for use in leading-edge computing, consumer, networking, embedded and mobile products. Micron's common stock is traded on the NASDAQ under the MU symbol. To learn more about Micron Technology, Inc., visit www.micron.com.

The Micron Technology, Inc. logo is available at http://www.globenewswire.com/newsroom/prs/?pkgid=6950

About TE Connectivity

TE Connectivity (NYSE:TEL) is a $13 billion world leader in connectivity. The company designs and manufactures products at the heart of electronic connections for the world's leading industries including automotive, energy and industrial, broadband communications, consumer devices, healthcare, and aerospace and defense. TE Connectivity's long-standing commitment to innovation and engineering excellence helps its customers solve the need for more energy efficiency, always-on communications and ever-increasing productivity. With nearly 90,000 employees in over 50 countries, TE Connectivity makes connections the world relies on to work flawlessly every day. To connect with the company, visit: www.TE.com.

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we believe that the expectations reflected in the forward-looking statements are reasonable, we cannot guarantee future results, levels of activity, performance or achievements.

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